

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1175cn8-5#pbf

(Engineering Calculation)

PDIIP

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**TOTAL MASS (g) : 0.498307**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001595	1000000	3200.83618164		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.149760	975000	300537.4375		
		Iron (Fe)	7439-89-6	0.003686	24000	7397.04199219		
		Phosphorus (P)	7723-14-0	0.000046	300	92.3125152588		
		Zinc (Zn)	7440-66-6	0.000108	700	216.733734131		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.153600</b>	<b>1000000</b>	<b>308243.53125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24904.8964844		
		<b>External Plating Total:</b>				<b>0.012410</b>	<b>1000000</b>	<b>24904.8964844</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2464.34277344		
<b>Internal Plating Total:</b>				<b>0.001228</b>	<b>1000000</b>	<b>2464.34277344</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000591	750000	1186.01525879		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000197	250000	395.338409424		
<b>Die Attach Total:</b>				<b>0.000788</b>	<b>1000000</b>	<b>1581.3536377</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.078816	240000	158167.453125		
		Bromine (Br)	40039-93-8	0.003284	10000	6590.31152344		
		Silica (SiO2)	60676-86-0	0.236448	720000	474502.40625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.009852	30000	19770.9316406		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.328400</b>	<b>1000000</b>	<b>659031.0625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000286	1000000	573.942993164		
					<b>TOTAL MASS (g) :</b>	<b>0.498307</b>		